wafer placement surface, wherein a temperature adjuster configured to adjust a temperature of the wafer placement surface is provided to be shared among the plurality of devices, wherein the method includes: upon switching of an inspection target device, (A) calculating a first operation amount by a feedback control operation, based on a temperature measured by a preceding temperature sensor, which is a temperature sensor corresponding to a target device that has been inspected, among the plurality of temperature sensors, and a target temperature; (B) calculating a second operation amount by the feedback control operation, based on a temperature measured by a next temperature sensor, which is a temperature sensor corresponding to a target device to be inspected next, among the plurality of temperature sensors, and a target temperature; (C) calculating an operation amount of the temperature adjuster upon the switching of the inspection target device by adding a value obtained by multiplying a variable α, which is 1 or less, by the first operation amount and a value obtained by multiplying 1−α by the second operation amount; and (D) outputting the operation amount of the temperature adjuster upon the switching of the inspection target device, and wherein the variable α decreases over time and a rate of decrease also decreases over time.

[0006] According to the present disclosure, in a case where a common temperature adjuster is used among a plurality of devices formed on a substrate to adjust temperatures measured by temperature sensors through feedback control while inspecting some of the devices, it is possible to stabilize a temperature measured by a temperature sensor corresponding to a next inspection target device at an early stage when switching a target device for inspection.

BRIEF DESCRIPTION OF DRAWINGS

[0007] FIG. 1 is a perspective view schematically illustrating a configuration of an inspection apparatus according to an embodiment.

FIG. 2 is a front view schematically illustrating the configuration of the inspection apparatus according to the embodiment.

FIG. 3 is a cross-sectional view schematically illustrating a configuration of a stage.

FIG. 4 is a top view of the stage.

FIG. 5 is a block diagram illustrating an example of a configuration of a controller that

as a PID (Proportional-Integral-Derivative) control operation based on the temperature measured by a temperature sensor corresponding to an inspection target device and a target temperature. Then, the temperature adjuster operates based on a calculation result, and the temperature measured by the temperature sensor is adjusted to the target temperature. Temperature adjustment by the temperature adjuster affects not only the inspection target device that is generating heat but also devices not being inspected that are not generating heat. Therefore, during inspection, devices not being inspected are at a temperature lower than the target temperature.

[0016] Accordingly, after stopping power supply to a preceding inspection target device and before starting power supply to a next inspection target device, if the operation amount of the temperature adjuster is abruptly switched from being based on a temperature measurement result of a temperature sensor corresponding to the preceding inspection target device to being based on a temperature measurement result of a temperature sensor corresponding to the next inspection target device, the following phenomenon occurs. That is, the temperature measured by the temperature sensor (hereinafter referred to as a "next temperature sensor") corresponding to the next inspection target device is not stabilized in a short time, resulting in overshoot or undershoot. In particular, when an amount of heat generated by the device is large, a time until the temperature measured by the next temperature sensor is stabilized becomes longer. If the temperature measured by the next temperature sensor is not stabilized, inspection of the next inspection target device is not performed, and thus throughput deteriorates. If a gain of the feedback control operation is reduced, it is possible to suppress the overshoot or undershoot. However, if the gain of the feedback control operation is reduced, it takes a long time until the temperature measured by the next temperature sensor reaches the target temperature, and as a result, throughput deteriorates. These issues are particularly significant in devices with large heat generation.

[0017] Therefore, a technique according to the present disclosure, in a case where a plurality of temperature sensors is installed on a substrate support and temperature control is performed by a single temperature adjuster, allows the temperature measured by the next temperature sensor to

W into contact with a probe 11a of the probe card 11.

[0022] In the accommodation chamber 2, the probe card 11 is disposed above the stage 10 so as to face the stage 10. The probe card 11 includes the probe 11a that electrically contacts an electrode and the like of a device formed on the wafer W. The probe card 11 is also connected to the tester 4 via an interface 12. Each probe 11a, during inspection of electrical characteristics, comes into contact with an electrode of each device formed on the wafer W, supplies power from the tester 4 to the device via the interface 12, and delivers a signal from the device to the tester 4 via the interface 12.

[0023] The loader 3 takes out the wafer W accommodated in a FOUP (Front Opening Unified Pod) (not shown), which is a transfer container, and transfers the wafer W to the stage 10 of the accommodation chamber 2. The loader 3 also receives the wafer W, for which inspection of electrical characteristics of the device has been completed, from the stage 10 and accommodates the wafer W in the FOUP.

[0024] The loader 3 includes a controller 13. The controller 13 processes computer-executable instructions that causes the inspection apparatus 1 to execute various processes described in the present disclosure. The controller 13 may be configured to control each element of the inspection apparatus 1 so as to execute the various processes described herein. In one embodiment, part or all of the controller 13 may be included in the inspection apparatus 1. The controller 13 may include a processor, a storage, and a communication interface. The controller 13 is realized, for example, by a computer. The processor may be configured to read, from the storage, a program providing logic or routines enabling various control operations, and to execute the read program to perform the various control operations. The program may be stored in advance in the storage or may be acquired via a medium when necessary. The acquired program is stored in the storage and is read from the storage and executed by the processor. The medium may be any of various computer-readable storage media or may be a communication line connected to the communication interface. The storage media may be transitory or non-transitory. The processor may be a central processing unit (CPU). The storage may include a random access memory (RAM), a read only memory (ROM), a hard disk

obtained by multiplying α (where α is a variable of 1 or less and decreases over time, and a rate of decrease also decreases over time) by the first operation amount PV1 of the temperature adjuster TM and the value obtained by multiplying (1−α) by the second operation amount PV2 of the temperature adjuster TM. The calculated operation amount PVs is output to the temperature adjustment controller 203 and used for the control of the temperature adjuster TM.

[0066] The target device that has been inspected, which corresponds to the preceding temperature sensor 111p, generates heat due to the power supply in the preceding inspection. However, since temperature adjustment is performed, the deviation δp between the temperature measured by the preceding temperature sensor 111p and the target temperature is small and is approximately zero. Therefore, the first operation amount PV1 of the temperature adjuster TM is also small. On the other hand, since the next inspection target device corresponding to the next temperature sensor 111n was not an inspection target in the preceding inspection, no heat is generated due to the absence of power supply. However, since a temperature adjustment same as that of the inspection target device that generates heat due to power supply is performed, the deviation δn between the temperature measured by the next temperature sensor 111n and the target temperature is relatively large. Therefore, the second operation amount PV2 of the temperature adjuster TM also becomes large. In particular, immediately after the switching of the inspection target device (specifically, immediately after starting temperature control upon the switching), the deviation δn is large, and the second operation amount PV2 of the temperature adjuster TM also becomes large.

[0067] Therefore, unlike the present embodiment, when the second operation amount PV2 of the temperature adjuster TM is continuously used upon the switching of the inspection target device for the control of the temperature adjuster TM from the beginning of the switching, the operation amount of the temperature adjuster TM becomes large in an initial stage of the switching, and a change in the temperature measured by the next temperature sensor 111n also becomes large. As a result, overshoot or undershoot occurs in the temperature measured by the next temperature sensor 111n. That is, a stabilization time of the temperature measured by the next temperature

sensor 111n becomes long.

[0068] In contrast, in the present embodiment, upon the switching of the inspection target device, not the second operation amount PV2 of the temperature adjuster TM but the operation amount PVs of the temperature adjuster TM upon the switching of the inspection target device is used for the control of the temperature adjuster TM. The operation amount PVs of the temperature adjuster TM upon the switching of the inspection target device is equal to or substantially equal to the first operation amount PV1 of the temperature adjuster TM in the initial stage of the switching. Further, as described above, the first operation amount PV1 of the temperature adjuster TM is small. That is, in the present embodiment, the operation amount of the temperature adjuster TM is small in the initial stage of the switching of the inspection target device. Therefore, according to the present embodiment, in the initial stage of the switching of the inspection target device, a change in the temperature measured by the next temperature sensor 111n is also small. As a result, overshoot or undershoot is less likely to occur in the temperature measured by the next temperature sensor 111n. Further, even when the gain in the feedback control operation is increased in order to cause the temperature measured by the next temperature sensor 111n to reach the target temperature at an early stage, the operation amount PVs of the temperature adjuster TM upon the switching of the inspection target device is small in the initial stage of the switching of the inspection target device. As a result, in the present embodiment, it is possible to increase the gain in the feedback control operation. Therefore, according to the present embodiment, upon the switching of the inspection target device, the temperature measured by the next temperature sensor 111n may reach the target temperature at an early stage while suppressing overshoot or undershoot. Therefore, according to the present embodiment, in a case in which the temperature adjuster TM that adjusts the temperature of the wafer placement surface 110a of the stage 10 is provided to be shared among a plurality of devices and the plurality of temperature sensors 111 are provided along the wafer placement surface 110a, it is possible to stabilize the temperature measured by the next temperature sensor 111n at an early stage.

[0069] In the feedback control operation, gain may be shared among the temperature sensors 111, as described above. In the present embodiment, even when a strong gain, which is shared among the temperature sensors 111, is employed as the gain in the feedback control operation, it is possible to suppress overshoot or undershoot in the temperature measured by the next temperature sensor 111n regardless of which of the plurality of temperature sensors 111 corresponds to the next temperature sensor 111n. When the gain in the feedback control operation is shared among the temperature sensors 111, setting of the gain is easily performed.

[0070] Further, by setting an appropriate variable α (specifically, a time constant T) based on an allowable time in the switching of the inspection target device (specifically, for example, an allowable index time), it is possible to stabilize the temperature measured by the next temperature sensor 111n within the allowable time.

[0071] Further, as described above, when changing the operation amounts used for the control of the heating plate 121 and the cooler CM from the operation amounts PVhs and PVcs upon the switching of the inspection target device to the second operation amounts PVh2 and PVc2, an integral value related to an integral control operation used to calculate the second operation amounts PVh2 and PVc2 may be maintained without being reset. As a result, it is possible to prevent occurrence of overshoot or undershoot in the temperature measured by the next temperature sensor 111n caused by resetting of the integral value. In other words, it is possible to prevent the time until the temperature measured by the next temperature sensor 111n is stabilized from being prolonged due to the resetting of the integral value.

[0072] <Another Example 1 of Controller>

FIG. 6 is a block diagram illustrating another example 1 of the configuration of the controller that controls the temperature adjuster TM. In the operation amount calculator 202 of the controller 13 in FIG. 5, the output operation amount calculator 213 also functions as an output. In contrast, an operation amount calculator 202A of a controller 13A in FIG. 6 includes an output 221 separately from an output operation amount calculator 213A.

[0073] The output operation amount calculator 213A differs from the output operation amount

the temperature sensors 111. Specifically, when the heating element is embedded only in the outer periphery of the heating plate 121, the dead time and the transfer model for the heating plate 121 differ between the temperature sensor 111 provided at the center of the wafer placement surface 110a and the temperature sensor 111 provided at the outer periphery of the wafer placement surface 110a. Further, for example, the dead time and the dead-time compensation amount δc for the cooler CM are shared among the temperature sensors 111. Specifically, when an operation amount of the cooler CM is related to the temperature of a refrigerant, the dead time for the cooler CM exists and the dead time and the dead-time compensation amount δc are shared among the temperature sensors 111.

[0081] In this example, a first operation amount calculator 211A and a second operation amount calculator 212A calculate the first operation amount PV1 and the second operation amount PV2 of the temperature adjuster TM based on the compensation amounts calculated by the dead-time compensator 231, respectively.

[0082] Specifically, the first operation amount calculator 211A calculates the first operation amount PVh1 of the heating plate 121 based on the dead-time compensation amount δh for the heating plate 121 corresponding to a dead time for the preceding temperature sensor 111p. More specifically, the first operation amount calculator 211A calculates a corrected deviation δp′ by adding the dead-time compensation amount δh for the heating plate 121 corresponding to the dead time for the preceding temperature sensor 111p to the deviation δp between the temperature measured by the preceding temperature sensor 111p and the target temperature. The first operation amount calculator 211A then calculates the first operation amount PVh1 of the heating plate 121 by the PID control operation based on the corrected deviation δp′.

[0083] Specifically, the second operation amount calculator 212A calculates the second operation amount PVh2 of the heating plate 121 based on the dead-time compensation amount δh for the heating plate 121 corresponding to a dead time for the next temperature sensor 111n. More specifically, the second operation amount calculator 212A calculates a corrected deviation δn′ by adding the dead-time compensation amount δh for the heating plate 121 corresponding to

the dead time for the next temperature sensor 111n to the deviation δn between the temperature measured by the next temperature sensor 111n and the target temperature. The second operation amount calculator 212A then calculates the second operation amount PVh2 of the heating plate 121 by the PID control operation based on the corrected deviation δn′.

[0084] Further, the first operation amount calculator 211A calculates the first operation amount PVc1 of the cooler CM based on the dead-time compensation amount δc for the cooler CM corresponding to a dead time which is shared among the temperature sensors 111. Specifically, the first operation amount calculator 211A calculates a corrected deviation δp′ by adding the dead-time compensation amount δc for the cooler CM corresponding to the dead time which is shared among the temperature sensors 111 to the deviation δp between the temperature measured by the preceding temperature sensor 111p and the target temperature. The first operation amount calculator 211A then calculates the first operation amount PVc1 of the cooler CM by the PID control operation based on the corrected deviation δp′.

[0085] Further, the second operation amount calculator 212A calculates the second operation amount PVc2 of the cooler CM based on the dead-time compensation amount δc for the cooler CM corresponding to the dead time which is shared among the temperature sensors 111. Specifically, the second operation amount calculator 212A calculates a corrected deviation δn′ by adding the dead-time compensation amount δc for the cooler CM corresponding to the dead time which is shared among the temperature sensors 111 to the deviation δn between the temperature measured by the next temperature sensor 111n and the target temperature. The second operation amount calculator 212A then calculates the second operation amount PVc2 of the cooler CM by the PID control operation based on the corrected deviation δn′.

[0086] As described above, the first operation amount calculator 211A and the second operation amount calculator 212A calculate the first operation amount PV1 and the second operation amount PV2 of the temperature adjuster TM, based on the compensation amounts calculated by the dead-time compensator 231, respectively, thereby enabling compensation for a temporal dead band.

wherein a temperature adjuster configured to adjust a temperature of the wafer placement surface is provided to be shared among the plurality of devices,

wherein the method includes:

upon switching of an inspection target device,

(A) calculating a first operation amount by a feedback control operation, based on a temperature measured by a preceding temperature sensor, which is a temperature sensor corresponding to a target device that has been inspected, among the plurality of temperature sensors, and a target temperature;

(B) calculating a second operation amount by the feedback control operation, based on a temperature measured by a next temperature sensor, which is a temperature sensor corresponding to a target device to be inspected next, among the plurality of temperature sensors, and a target temperature;

(C) calculating an operation amount of the temperature adjuster upon the switching of the inspection target device by adding a value obtained by multiplying a variable α, which is 1 or less, by the first operation amount and a value obtained by multiplying 1−α by the second operation amount; and

(D) outputting the operation amount of the temperature adjuster upon the switching of the inspection target device, and

wherein the variable α decreases over time and a rate of decrease also decreases over time.

(2) The method according to (1), wherein the variable α decreases exponentially.

(3) The method according to (1), wherein the variable α is defined by Equation (X) below:

$$\alpha = e^{-t/T} \quad \ldots (X)$$

where T is a predetermined time constant and t is an elapsed time after completion of preceding inspection.

(4) The method according to any one of (1) to (3), wherein (D) includes performing base clipping on the operation amount of the temperature adjuster upon the switching of the inspection target device so as not to fall within a dead band, and outputting a base-clipped operation amount.

(5) The method according to (4), wherein the base-clipped operation amount has hysteresis.

(6) The method of any one of (1) to (5), further including:

(E) calculating, using a Smith method, a compensation amount corresponding to a dead time included in a transfer system from input of the operation amount of the temperature adjuster to output of a temperature measurement result by a corresponding temperature sensor among the plurality of temperature sensors,

wherein (A) and (B) include calculating the first operation amount and the second operation amount, respectively, based on the compensation amount.

(7) The method according to (6),

wherein (E) includes calculating a compensation amount corresponding to the dead time related to the preceding temperature sensor and a compensation amount corresponding to the dead time related to the next temperature sensor,

wherein (A) includes calculating the first operation amount based on the compensation amount corresponding to the dead time related to the preceding temperature sensor, and

wherein (B) includes calculating the second operation amount based on the compensation amount corresponding to the dead time related to the next temperature sensor.

(8) The method of any one of (1) to (7), wherein, when an operation amount used for control of the temperature adjuster is switched to the second operation amount from the operation amount of the temperature adjuster upon the switching of the inspection target device, an integral value related to an integral control operation used for calculating the second operation amount is maintained without being reset.

(9) An inspection apparatus for inspecting a plurality of devices formed on a substrate, the inspection apparatus including:

a substrate support including a wafer placement surface on which the substrate is placed and a plurality of temperature sensors provided along the wafer placement surface;

a temperature adjuster configured to adjust a temperature of the wafer placement surface and provided to be shared among the plurality of devices;

a first operation amount calculator configured to calculate, upon switching of an inspection target device, a first operation amount by a feedback control operation, based on a temperature measured by a preceding temperature sensor, which is a temperature sensor corresponding to a target device that has been inspected, among the plurality of temperature sensors, and a target temperature;

a second operation amount calculator configured to calculate, upon the switching of the inspection target device, a second operation amount by the feedback control operation, based on a temperature measured by a next temperature sensor, which is a temperature sensor corresponding to a target device to be inspected next, among the plurality of temperature sensors, and a target temperature;

an output operation amount calculator configured to calculate an operation amount of the temperature adjuster upon the switching of the inspection target device by adding a value obtained by multiplying a variable α, which is 1 or less, by the first operation amount and a value obtained by multiplying 1−α by the second operation amount; and

an output configured to output the operation amount of the temperature adjuster upon the switching of the inspection target device,

wherein the variable α decreases over time and a rate of decrease also decreases over time.

(10) The inspection apparatus according to (9), wherein the variable α decreases exponentially.

(11) The inspection apparatus according to (9), wherein the variable α is defined by Equation (X) below:

$$\alpha = e^{-t/T} \ldots (X)$$

where T is a predetermined time constant and t is an elapsed time after completion of preceding inspection.

(12) The inspection apparatus according to any one of (9) to (11), wherein the output performs base clipping on the operation amount of the temperature adjuster upon the switching of the inspection target device so as not to fall within a dead band, and outputs a base-clipped operation

amount.

(13) The inspection apparatus according to (12), wherein the base-clipped operation amount has hysteresis.

(14) The inspection apparatus according to any one of (9) to (13), further including:

a dead-time compensator configured to calculate, using a Smith method, a compensation amount corresponding to a dead time included in a transfer system from input of the operation amount of the temperature adjuster to output of a temperature measurement result by a corresponding temperature sensor among the plurality of temperature sensors,

wherein the first operation amount calculator and the second operation amount calculator calculate the first operation amount and the second operation amount, respectively, based on the compensation amount.

(15) The inspection apparatus according to (14), wherein the dead-time compensator calculates a compensation amount corresponding to the dead time related to the preceding temperature sensor and a compensation amount corresponding to the dead time related to the next temperature sensor,

wherein the first operation amount calculator calculates the first operation amount based on the compensation amount corresponding to the dead time related to the preceding temperature sensor, and

wherein the second operation amount calculator calculates the second operation amount based on the compensation amount corresponding to the dead time related to the next temperature sensor.

(16) The inspection apparatus according to any one of (9) to (15), wherein, when an operation amount used for control of the temperature adjuster is switched to the second operation amount from the operation amount of the temperature adjuster upon the switching of the inspection target device, an integral value related to an integral control operation used for calculating the second operation amount is maintained without being reset.

EXPLANATION OF REFERENCE NUMERALS

[0092] 1: inspection apparatus, 10: stage, 110a: upper surface (wafer placement surface), 111: temperature sensor, 211, 211A: first operation amount calculator, 212, 212A: second operation

WHAT IS CLAIMED IS:

1. A method of adjusting a temperature of a substrate support that supports a substrate when inspecting a plurality of devices formed on the substrate,

wherein the substrate support includes a wafer placement surface on which the substrate is placed and a plurality of temperature sensors provided along the wafer placement surface,

wherein a temperature adjuster configured to adjust a temperature of the wafer placement surface is provided to be shared among the plurality of devices,

wherein the method comprises:

upon switching of an inspection target device,

(A) calculating a first operation amount by a feedback control operation, based on a temperature measured by a preceding temperature sensor, which is a temperature sensor corresponding to a target device that has been inspected, among the plurality of temperature sensors, and a target temperature;

(B) calculating a second operation amount by the feedback control operation, based on a temperature measured by a next temperature sensor, which is a temperature sensor corresponding to a target device to be inspected next, among the plurality of temperature sensors, and a target temperature;

(C) calculating an operation amount of the temperature adjuster upon the switching of the inspection target device by adding a value obtained by multiplying a variable α, which is 1 or less, by the first operation amount and a value obtained by multiplying 1−α by the second operation amount; and

(D) outputting the operation amount of the temperature adjuster upon the switching of the inspection target device, and

wherein the variable α decreases over time and a rate of decrease also decreases over time.

2. The method of Claim 1, wherein the variable α decreases exponentially.

3. The method of Claim 1, wherein the variable α is defined by Equation (X) below:

$$\alpha = e^{-t/T} \ldots (X)$$

where T is a predetermined time constant and t is an elapsed time after completion of preceding inspection.

4. The method of any one of Claims 1 to 3, wherein (D) includes performing base clipping on the operation amount of the temperature adjuster upon the switching of the inspection target device so as not to fall within a dead band, and outputting a base-clipped operation amount.

5. The method of Claim 4, wherein the base-clipped operation amount has hysteresis.

6. The method of any one of Claims 1 to 3, further comprising:

(E) calculating, using a Smith method, a compensation amount corresponding to a dead time included in a transfer system from input of the operation amount of the temperature adjuster to output of a temperature measurement result by a corresponding temperature sensor among the plurality of temperature sensors,

wherein (A) and (B) include calculating the first operation amount and the second operation amount, respectively, based on the compensation amount.

7. The method of Claim 6,

wherein (E) includes calculating a compensation amount corresponding to the dead time related to the preceding temperature sensor and a compensation amount corresponding to the dead time related to the next temperature sensor,

wherein (A) includes calculating the first operation amount based on the compensation amount corresponding to the dead time related to the preceding temperature sensor, and

wherein (B) includes calculating the second operation amount based on the compensation amount corresponding to the dead time related to the next temperature sensor.

8. The method of any one of Claims 1 to 3, wherein, when an operation amount used for control of the temperature adjuster is switched to the second operation amount from the operation amount of the temperature adjuster upon the switching of the inspection target device, an integral value related to an integral control operation used for calculating the second operation amount is maintained without being reset.

9. An inspection apparatus for inspecting a plurality of devices formed on a substrate, the inspection apparatus comprising:

a substrate support including a wafer placement surface on which the substrate is placed and a plurality of temperature sensors provided along the wafer placement surface;

a temperature adjuster configured to adjust a temperature of the wafer placement surface and provided to be shared among the plurality of devices;

a first operation amount calculator configured to calculate, upon switching of an inspection target device, a first operation amount by a feedback control operation, based on a temperature measured by a preceding temperature sensor, which is a temperature sensor corresponding to a target device that has been inspected, among the plurality of temperature sensors, and a target temperature;

a second operation amount calculator configured to calculate, upon the switching of the inspection target device, a second operation amount by the feedback control operation, based on a temperature measured by a next temperature sensor, which is a temperature sensor corresponding to a target device to be inspected next, among the plurality of temperature sensors, and a target temperature;

an output operation amount calculator configured to calculate an operation amount of the temperature adjuster upon the switching of the inspection target device by adding a value

obtained by multiplying a variable α, which is 1 or less, by the first operation amount and a value obtained by multiplying 1−α by the second operation amount; and

an output configured to output the operation amount of the temperature adjuster upon the switching of the inspection target device,

wherein the variable α decreases over time and a rate of decrease also decreases over time.

10. The inspection apparatus of Claim 9, wherein the variable α decreases exponentially.

11. The inspection apparatus of Claim 9, wherein the variable α is defined by Equation (X) below:

$$\alpha = e^{-t/T} \ldots (X)$$

where T is a predetermined time constant and t is an elapsed time after completion of preceding inspection.

12. The inspection apparatus of any one of Claims 9 to 11, wherein the output performs base clipping on the operation amount of the temperature adjuster upon the switching of the inspection target device so as not to fall within a dead band, and outputs a base-clipped operation amount.

13. The inspection apparatus of Claim 12, wherein the base-clipped operation amount has hysteresis.

14. The inspection apparatus of any one of Claims 9 to 11, further comprising:

a dead-time compensator configured to calculate, using a Smith method, a compensation amount corresponding to a dead time included in a transfer system from input of the operation amount of the temperature adjuster to output of a temperature measurement result

by a corresponding temperature sensor among the plurality of temperature sensors,

wherein the first operation amount calculator and the second operation amount calculator calculate the first operation amount and the second operation amount, respectively, based on the compensation amount.

15. The inspection apparatus of Claim 14, wherein the dead-time compensator calculates a compensation amount corresponding to the dead time related to the preceding temperature sensor and a compensation amount corresponding to the dead time related to the next temperature sensor,

wherein the first operation amount calculator calculates the first operation amount based on the compensation amount corresponding to the dead time related to the preceding temperature sensor, and

wherein the second operation amount calculator calculates the second operation amount based on the compensation amount corresponding to the dead time related to the next temperature sensor.

16. The inspection apparatus of any one of Claims 9 to 11, wherein, when an operation amount used for control of the temperature adjuster is switched to the second operation amount from the operation amount of the temperature adjuster upon the switching of the inspection target device, an integral value related to an integral control operation used for calculating the second operation amount is maintained without being reset.